Transient Voltage Suppressors (TVS) Data Sheet

Features

- For surface mounted applications in order to optimize board space
- Low profile package
- Built-in strain relief
- Low inductance
- Excellent clamping capability
- 600W peak pulse power capability at 10/1000μs waveform, repetitionrate (duty cycle):0.01%
- Fast response time
- Typical I_R less than 200μA
- High Temperature soldering: 260℃/10 seconds at terminals
- Plastic package has underwriters laboratory flammability 94V-0
- Meets MSL level 1, per J-STD-020
- Safety certification: UL: E465643

Mechanical Data

- Case: JEDEC DO-214AA.
- Terminal: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode
- Standard Packaging: 12mm tape (EIA STD RS-481)
- Weight: 0.10g

Applications

- I/O interface
- Power supply

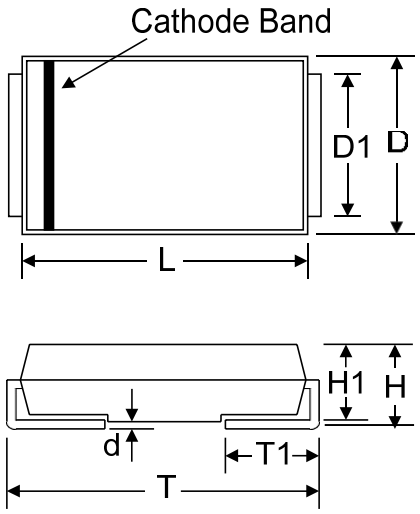
Maximum Ratings and Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.

Rating	Symbol	Value	Units
Peak pulse power dissipation at 10/1000μs waveform (Note1, Note2, Fig.1)	P_{PPM}	Minimum 600	Watts
Peak pulse current of at 10/1000μs waveform (Note 1, Fig.3)	I_{PPM}	50	Amps
Steady state power dissipation at T_A=50℃(Fig.5)	$P_{M(AV)}$	5.0	Watts
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6)	I_{FSM}	100	Amps
Operating junction and Storage Temperature Range.	T_J,T_{STG}	-65 to +150	℃
Typical thermal resistance junction to lead	$R_{\theta JL}$	20	℃/W
Typical thermal resistance junction to ambient	$R_{\theta JA}$	100	℃/W

Notes: 1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25℃ per Fig.2.
2. Mounted on 5.0mm×5.0mm (0.03mm thick) copper pads to each terminal.
3. 8.3ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.

Dimensions (SMB/DO-214AA)

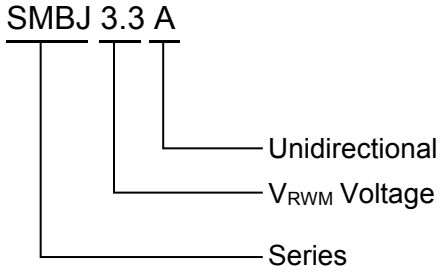


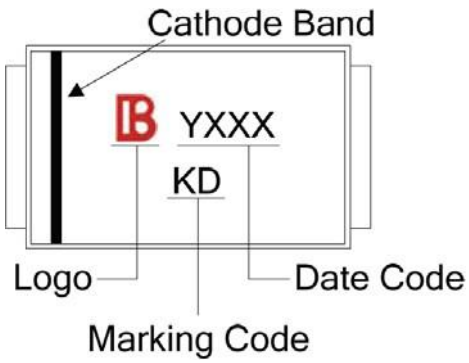
Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
L	4.06	4.57	0.160	0.180
D	3.30	3.94	0.130	0.155
D1	1.95	2.20	0.077	0.086
T	5.21	5.59	0.205	0.220
T1	0.76	1.52	0.030	0.060
d	-	0.203	-	0.008
H	2.15	2.65	0.085	0.104
H1	2.13	2.47	0.084	0.097

Electrical Characteristics (T_A=25℃)

Part Number	Device Marking Code	Reverse Stand-Off Voltage	Breakdown Voltage @I_T	Test Current	Maximum Clamping Voltage @I_{PP}10/1000μs		Maximum Clamping Voltage @I_{PP}8/20μs		Reverse Leakage @V_{RWM}	Typical Junction Capacitance @1MHz 100mV
		V_{RWM}(V)	V_{BR}(V)	I_T(mA)	V_C(V)	I_{PP}(A)	V_C(V)	I_{PP}(A)	I_R(μA)	C_J(pF)
SMBJ3.3A	KD	3.3	4.1-6.0	1.0	7.3	50	11.3	200	200	5900

Part Number Code and Marking





Ratings and Characteristic Curves (T_A=25℃ unless otherwise noted)

Figure 1. Peak Pulse Power Rating Curve

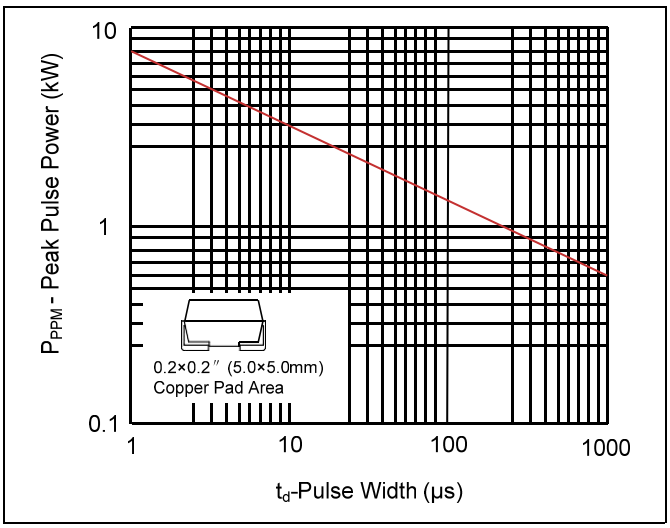


Figure 2. Pulse Derating Curve

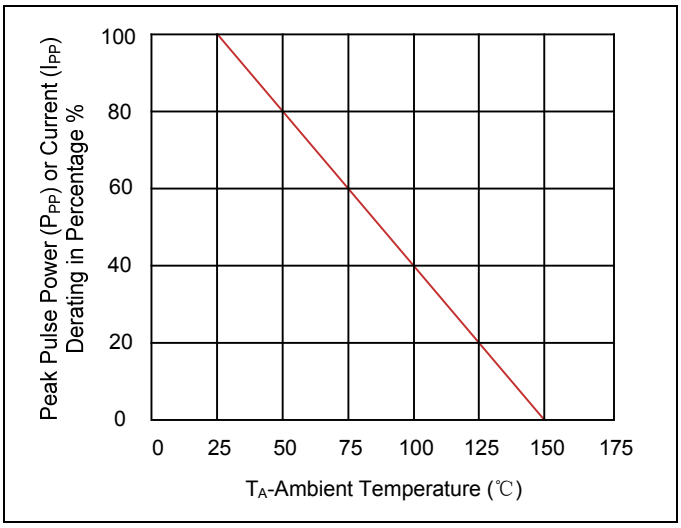


Figure 3. Pulse Waveform

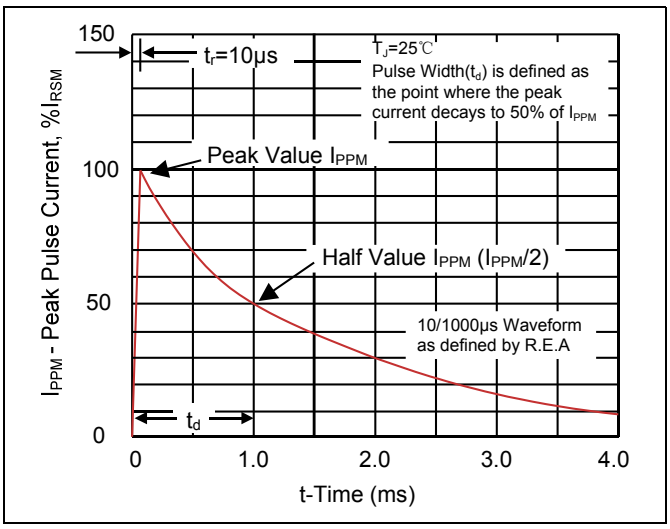


Figure 4. Typical Junction Capacitance

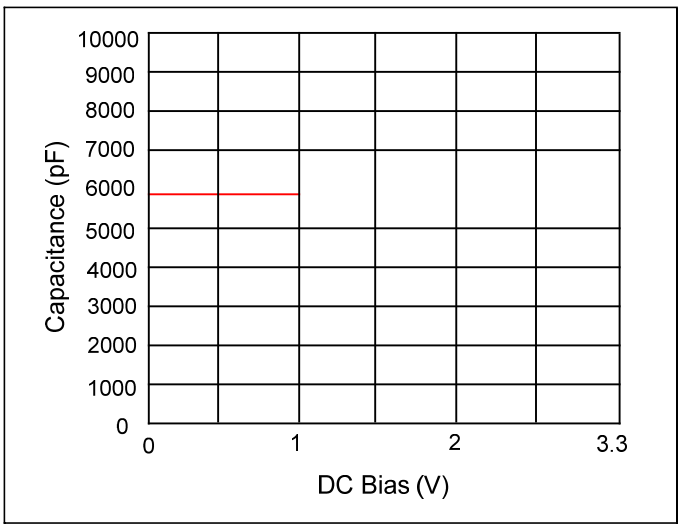


Figure 5. Steady State Power Dissipation Derating Curve

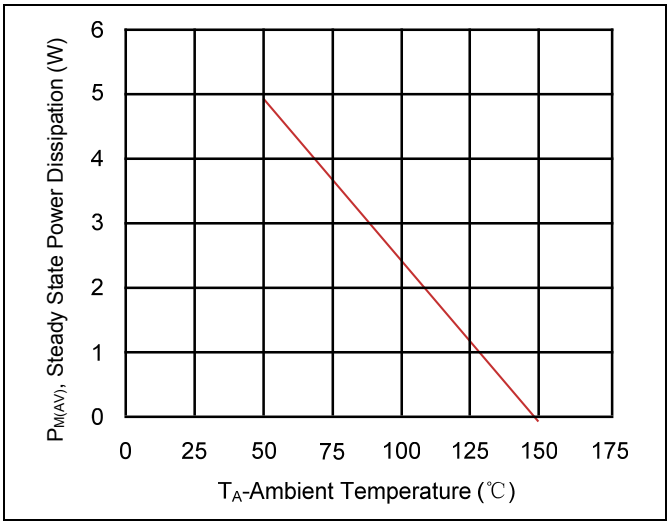
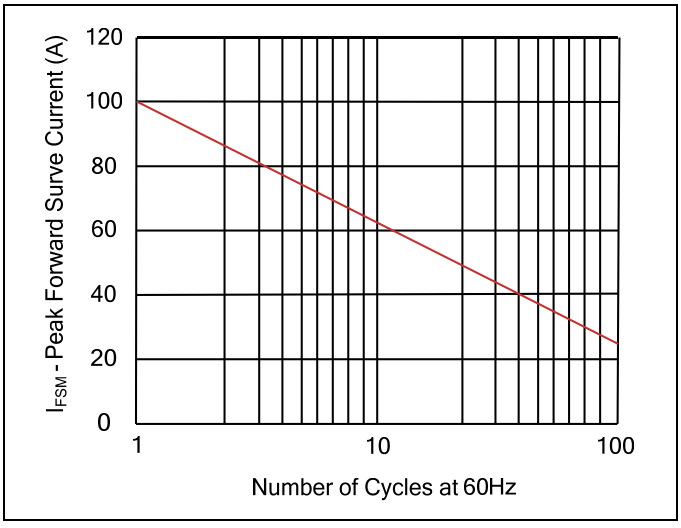
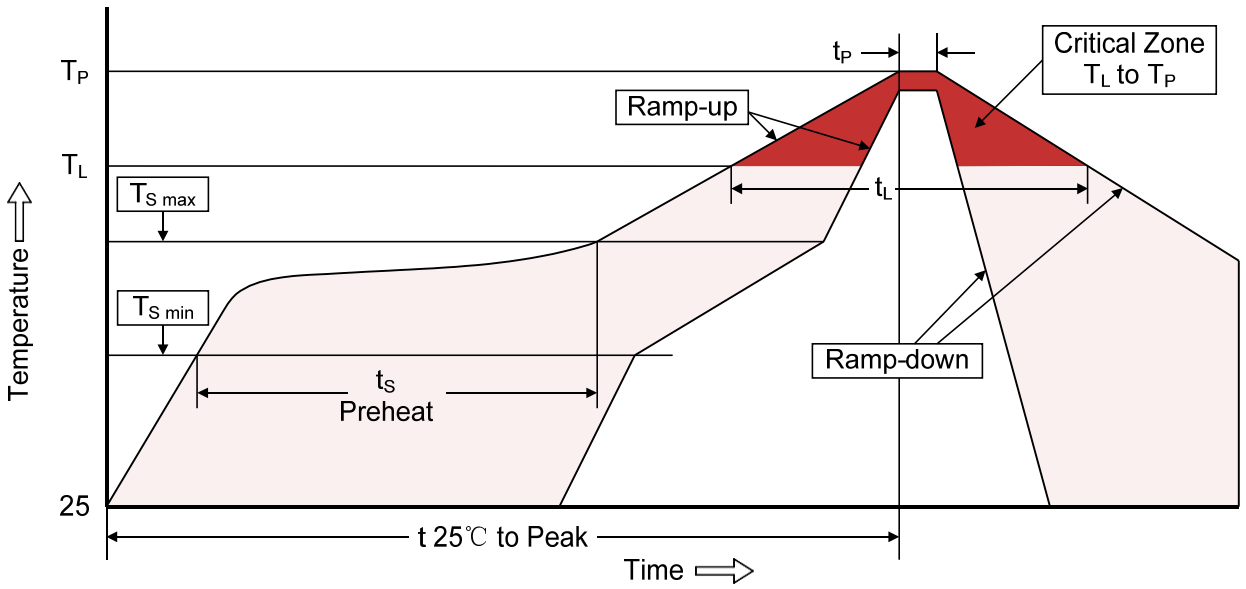


Figure 6. Maximum Non-Repetitive Forward Surge Current



Recommended Soldering Conditions

Reflow Soldering

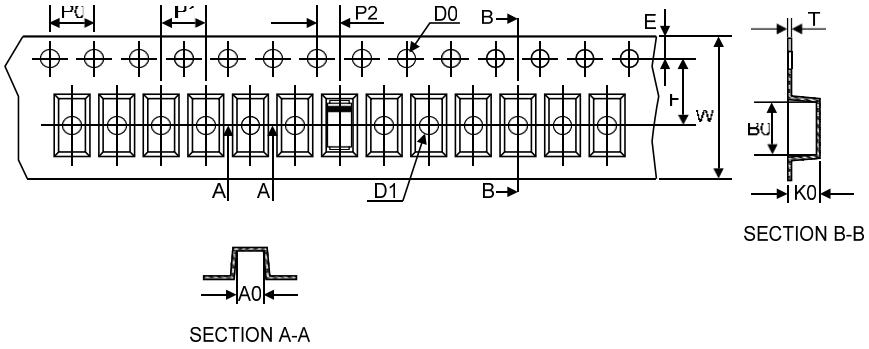


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate ($T_L$to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual PeakTemperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

Packaging

Tape

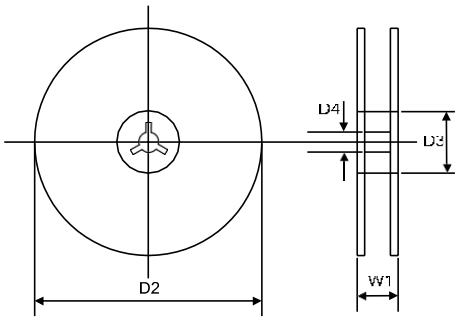


SECTION A-A

SECTION B-B

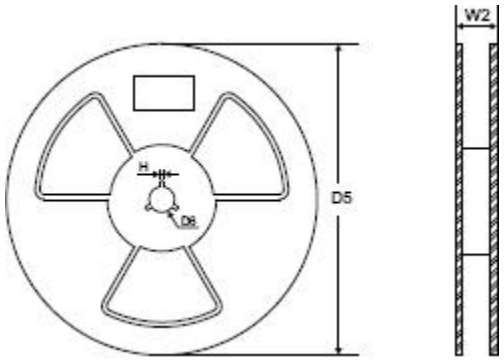
Symbol	Dimension (mm)
W	12.00±0.20
P0	4.00±0.10
P1	8.00±0.10
P2	2.00±0.10
D0	Φ1.55±0.10
D1	Φ1.5±0.10
E	1.75±0.10
F	5.50±0.05
A0	3.86±0.10
B0	5.65±0.10
K0	2.75±0.15
T	0.25±0.05

7”Reel



D2	Φ178.0±2.0
D3	Φ50.0Min.
D4	Φ13.0±0.5
W1	16.0±2.0
Quantity: 500PCS	

13”Reel



D5	Φ330.0±2.0
D6	Φ13.5±0.5
H	2.5±1.0
W2	16.0±2.0
Quantity: 3000PCS	